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## SEMICONDUCTOR DEVICE

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Applicant(s): FUJITSU LTD  
Requested Patent: ☐ JP5166992  
Application Number: JP19910330742 19911213  
Priority Number(s):  
IPC Classification: H01L23/50; B65D85/00; B65D85/38  
EC Classification:  
Equivalents:

### Abstract

**PURPOSE:** To accurately position a semiconductor device which is delivered as it is mounted on a protective frame by the use of protective frame.

**CONSTITUTION:** A semiconductor main body 16, a frame 18 provided outside outer leads 14b so as to surround the semiconductor main body 16, and a support 19 provided between the semiconductor main body 16 and the frame 18 to support the semiconductor main body 16 on the frame 18 are provided, where the frame 18 and the support 19 constitute a protective frame 17 of integral structure.

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CLAIMS

- [Claim(s)]
- [Claim 1] The main part of a semiconductor device (16) characterized by providing the following, and the frame section arranged so that this main part of a semiconductor device (16) may be surrounded in an outside [ outer lead / this / (14b) ] position (18 23). While having this frame section (18 23) and the supporter (19) which makes this frame section (18 23) support \*\*\*\*\* , now cage this the main part of a semiconductor device (16) between these main parts of a semiconductor device (16) The semiconductor device characterized by for this frame section (18 23) and this supporter (19) resembling the protection frame (17 24) which metal material comes to form with the aforementioned die pad (12) in one, and constituting them more. Semiconductor device (11) The die pad which carries this semiconductor device (11) (12) The package made of a resin which closes this semiconductor device (11) (13) Two or more leads constituted by the inner lead (14a) connected to this semiconductor device (11), and the outer lead (14b) which extended to the exterior of this package made of a resin (13) (14)
- [Claim 2] The semiconductor device of the claim 1 which forms the guide holes (20) for positioning this main part of a semiconductor device (16) in this protection frame (17), and is characterized by the bird clapper.
- [Claim 3] The claim 1 which forms the bending section (22) in this protection frame (24), and is characterized by the bird clapper, or 2 semiconductor devices.
- [Claim 4] This outer lead (14b) is the semiconductor device of the claim 3 which this bending section (22) has the bending direction selected in the direction which protects this outer lead (14b), and is characterized by the bird clapper by carrying out bending formation at the predetermined configuration.
- [Claim 5] the claim 1 characterized by arranging an insulating resin tape (25) in a part of this frame section (18 24), or 4 -- inner -- a semiconductor device given in either
- [Claim 6] The metal supporter material formed so that it might extend towards an outside in [ main part / (16) / this / the main part of a semiconductor device (16) characterized by providing the following, and / of a semiconductor device ] one (31), While being arranged so that this main part of a semiconductor device (16) may be surrounded in an outside [ outer lead / this / (14b) ] position The metal protection frame member (34 32- 37) which supports this main part of a semiconductor device (16) through this supporter material (31) by fixing this supporter material (31), and the semiconductor device characterized by being alike and being constituted more. Semiconductor device (11) The die pad which carries this semiconductor device (11) (12) The package made of a resin which closes this semiconductor device (11) (13) Two or more leads constituted by the inner lead (14a) connected with this semiconductor device (11), and the outer lead (14b) which extended to the exterior of this package made of a resin (13) (14)
- [Claim 7] The semiconductor device of the claim 6 which forms the guide holes (20) for positioning this main part of a semiconductor device (16) in this protection frame member (34 32- 37) or this supporter material (31), and is characterized by the bird clapper.
- [Claim 8] The claim 6 which forms the bending section (35) in this protection frame member (34), and is characterized by the bird clapper, or 7 semiconductor devices.
- [Claim 9] This outer lead (14b) is the semiconductor device of the claim 8 which this bending section (35) has the bending direction selected in the direction which protects this outer lead (14b), and is characterized by the bird clapper by carrying out bending formation at the predetermined configuration.
- [Claim 10] The claim 6 characterized by arranging an insulating resin tape (25) in a part of this protection frame member (34 32- 37), or 9 semiconductor devices.
- [Claim 11] This supporter material (31) is the claim 6 or the semiconductor device of 10 characterized by being fixed to a protection frame member (34 32- 37) by the welding means.
- [Claim 12] The frame section arranged so that this main part of a semiconductor device (16) may be surrounded in the main part of a semiconductor device (16) characterized by providing the following, and an outside [ outer lead / this / (14b) ] position (18). While having this frame section (18) and the supporter (19) which makes this frame section (18) support \*\*\*\*\* , now cage this the main part of a semiconductor device (16) between these main parts of a semiconductor device (16) The 1st protection frame member to which metal material comes to form this frame section (18) and this supporter (19) in one (51), The semiconductor device characterized by being constituted by the 2nd and 3rd protection frame members (52 53) arranged so that it may superimpose on the upper part and lower part with each on both sides of this frame section (18). Semiconductor device (11) The die pad which carries this semiconductor device (11) (12) The package made of a resin which closes this semiconductor device (11) (13) Two or more leads constituted by the inner lead (14a) connected with this semiconductor device (11), and the outer lead (14b) which extended to the exterior of this package made of a resin (13).
- [Claim 13] this -- the semiconductor device of the claim 12 which forms the guide holes (20) for positioning this main part of a semiconductor device (16) to the 1st or 3rd protection frame member (51-53) or this supporter (19), and is characterized by the bird clapper
- [Claim 14] this -- the claim 12 which forms the bending section (35) at least in one side of the 2nd or 3rd protection frame member (52 53), and is characterized by the bird clapper, or the semiconductor device of 13

[Claim 15] This outer lead (14b) is the semiconductor device of the claim 14 which this bending section (35) has the bending direction selected in the direction which protects this outer lead (14b), and is characterized by the bird clapper by carrying out bending formation at the predetermined configuration.

[Claim 16] this -- the claim 12 characterized by arranging an insulating resin tape (25) in a part of the 1st or 3rd protection frame member (51-53), or 15 -- inner -- a semiconductor device given in either

[Claim 17] this -- the claim 12 which the 1st or 3rd protection frame member (51-53) is fixed by the welding means in one, and is characterized by the bird clapper, or 16 -- inner -- a semiconductor device given in either

[Claim 18] this -- the 1st protection frame member (51) -- this -- with a welding position with the 2nd protection frame member (52) A welding position with the 3rd protection frame member (53) is selected in a different position. this -- the 1st protection frame member (51) -- this -- A hole (54) is formed. this -- the protection frame member (51) of the above 1st of the 3rd protection frame member (53) -- this -- a welding position with the 2nd protection frame member (52), and the position which counters -- the 1st recess -- A hole (55) is formed. this -- the protection frame member (51) of the above 1st of the 2nd protection frame member (52) -- this -- a welding position with the 3rd protection frame member (53), and the position which counters -- the 2nd recess -- A laser beam is irradiated. this -- the 1st and 2nd recess -- so that a hole (54 55) may be passed this -- the 1st protection frame member (51) -- this -- the 2nd protection frame member (52) -- and -- this -- the 1st protection frame member (51) -- this -- the semiconductor device according to claim 17 which carries out laser welding of the 3rd protection frame member (53), and is characterized by the bird clapper

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[Translation done.]

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DESCRIPTION OF DRAWINGS

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[Brief Description of the Drawings]

- [Drawing 1] It is drawing showing the semiconductor device which is the 1st example of this invention.
- [Drawing 2] It is drawing showing the modification of the semiconductor device which is the 1st example of this invention.
- [Drawing 3] It is drawing showing an example of the bending section.
- [Drawing 4] It is drawing showing the state where the insulating tape was arranged in the semiconductor device shown in drawing 2.
- [Drawing 5] It is drawing showing the semiconductor device which is the 2nd example of this invention.
- [Drawing 6] It is the exploded view showing the semiconductor device which is the 2nd example of this invention.
- [Drawing 7] a protection frame -- it is drawing showing other examples of composition of a member
- [Drawing 8] a protection frame -- it is drawing showing other examples of composition of a member
- [Drawing 9] It is drawing showing the example which made leadframe structure supporter material and the protection frame member.
- [Drawing 10] It is drawing showing the semiconductor device which is the 3rd example of this invention.
- [Drawing 11] It is drawing showing the example which applied this invention to the semiconductor device which has various structures.
- [Drawing 12] It is drawing showing the example which applied this invention to the semiconductor device which has various structures.
- [Drawing 13] It is drawing showing the example which applied this invention to the semiconductor device which has various structures.
- [Drawing 14] It is drawing for explaining an example of the conventional semiconductor device.
- [Description of Notations]
- 10, 21, 30, 50 Semiconductor device
- 11 Semiconductor Device
- 12 Die Pad
- 13 Package
- 14 Lead
- 14a Inner lead
- 14b Outer lead
- 15 Wire
- 16 Main Part of Semiconductor Device
- 17 24 Protection frame
- 18 23 Frame section
- 19 Supporter
- 20, 40, 41 Guide holes
- 22 35 Bending section
- 25 Insulating Tape
- 31 36 Supporter material
- 32, 33, 34, and 37 a protection frame -- member
- 38 39 Leadframe
- 51 1st Protection Frame -- Member
- 52 2nd Protection Frame -- Member
- 53 3rd Protection Frame -- Member
- 54 The 1st Escapes and it is Hole.
- 55 The 2nd Escapes and it is Hole.

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B 6 5 D 85/00	P	8921-3E		
85/38	J	8921-3E		

審査請求 未請求 請求項の数18(全 10 頁)

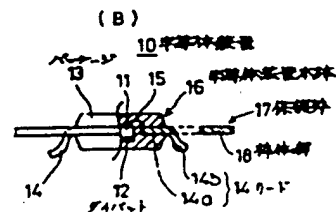
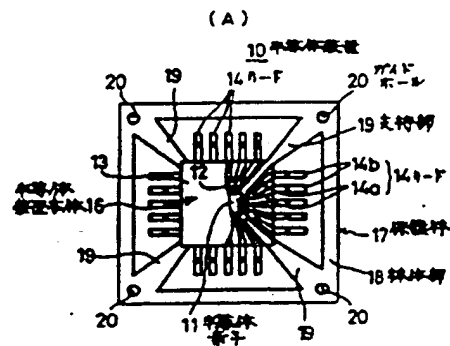
(21) 出願番号	特願平3-330742	(71) 出願人	000005223 富士通株式会社 神奈川県川崎市中原区上小田中1015番地
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		(74) 代理人	弁理士 伊東 忠彦 (外2名)

(54) 【発明の名称】 半導体装置

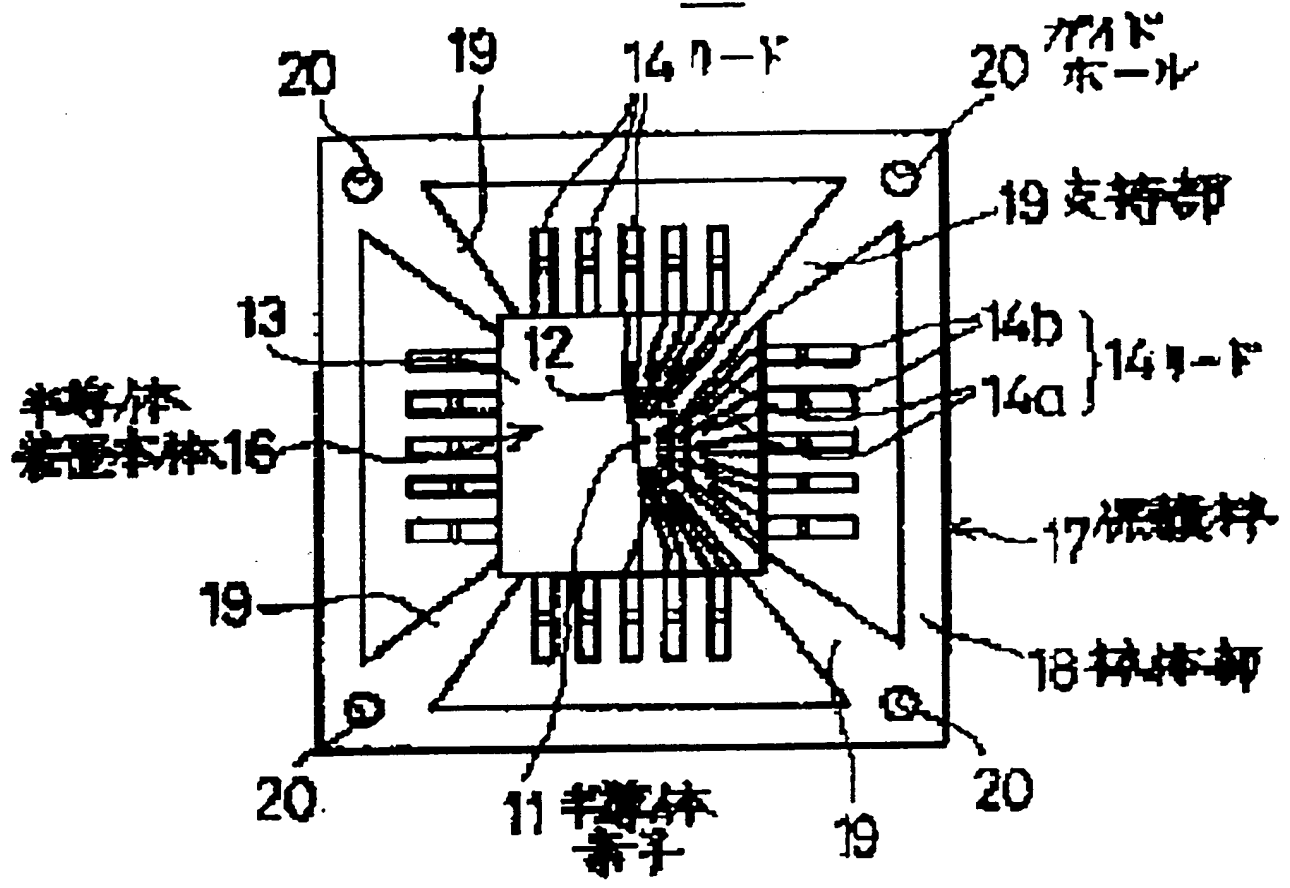
(57) 【要約】

【目的】 本発明は保護枠に取り付けられた状態で出荷される半導体装置に関し、保護枠により高精度の位置決めを行うことを目的とする。

【構成】 半導体装置本体16と、アウターリード14bより外側位置に半導体装置本体16を囲繞するように配設される枠体部18と、この枠体部18と半導体装置本体16との間に配設されており半導体装置本体16を枠体部18に支持させる支持部19とを有すると共に、枠体部18と支持部19とが金属材料により一体的に形成されてなる保護枠17により構成する。

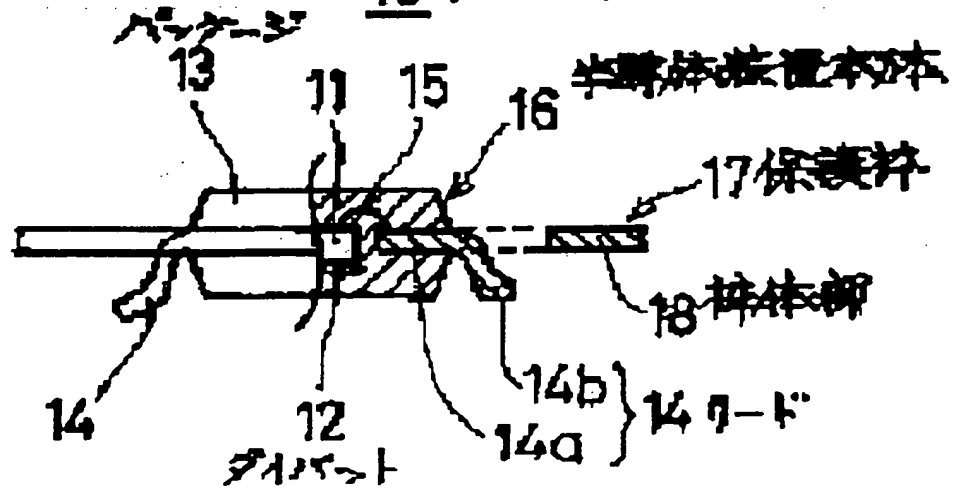


# 10 半導体装置



(B)

# 10 半導体装置



14

【図 12】本発明を種々の構造を有する半導体装置に適用した例を示す図である。

【図 13】本発明を種々の構造を有する半導体装置に適用した例を示す図である。

【図14】従来の半導体装置の一例を説明するための図である。

【符号の説明】

10, 21, 30, 50 半導體裝置

## 11 半導體素子

## 12 ダイバッド

### 13 バックページ

## 14 リード

14a インナーリード

14b アウターリード

15 ワイヤ

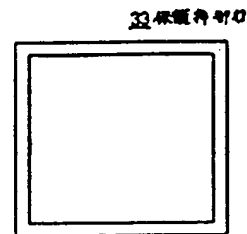
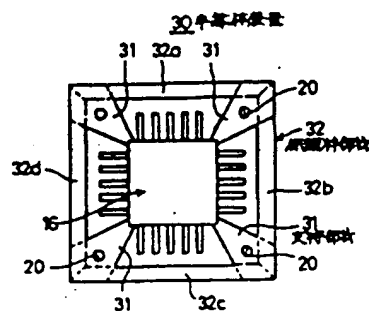
## 16 半导体装置本体

17. 24 保護棒

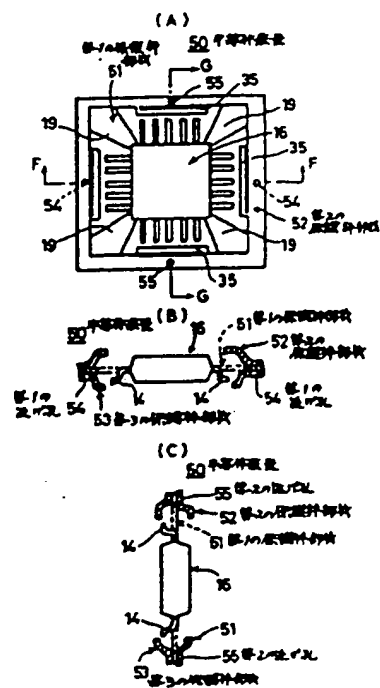
18, 23 桡体部

【图 5】

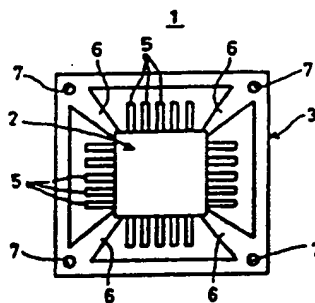
【圖 7】



【 1 0 】



【圖 14】



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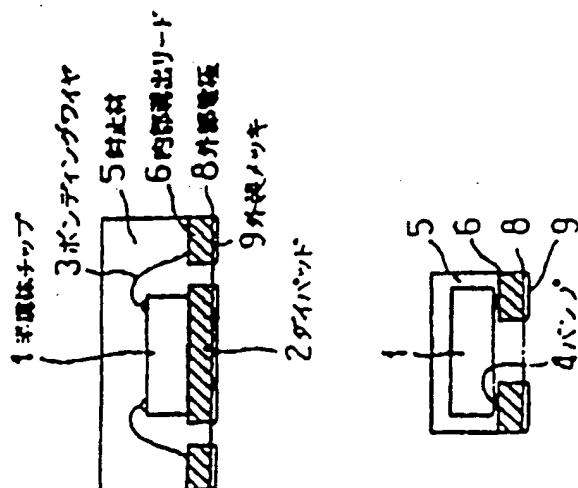
Mould package flat-face mounting type semiconductor device -  
exposes bottom surfaces of die pad and inner leads of bottom surface  
of mould package semiconductor device to be directly connected to  
circuit pattern of PCB NoAbstract

SONY CORP 91.11.06 91JP-289882

(93.05.25) H01L 23/28, 23/12, 23/28, 23/50

(6pp Dwg.No.1/13)  
N98-155203

U11-D01A3 U11-D03A9



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